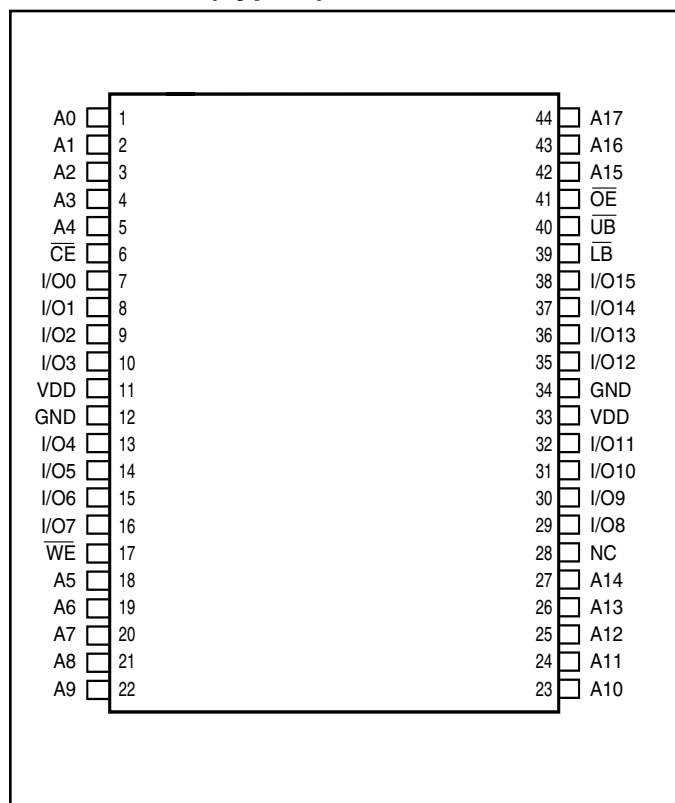


## TRUTH TABLE

| Mode            | $\overline{WE}$ | $\overline{CE}$ | $\overline{OE}$ | $\overline{LB}$ | $\overline{UB}$ | I/O PIN   |            | $V_{DD}$ Current      |
|-----------------|-----------------|-----------------|-----------------|-----------------|-----------------|-----------|------------|-----------------------|
|                 |                 |                 |                 |                 |                 | I/O0-I/O7 | I/O8-I/O15 |                       |
| Not Selected    | X               | H               | X               | X               | X               | High-Z    | High-Z     | $I_{SB1}$ , $I_{SB2}$ |
| Output Disabled | H               | L               | H               | X               | X               | High-Z    | High-Z     | $I_{CC}$              |
|                 | X               | L               | X               | H               | H               | High-Z    | High-Z     |                       |
| Read            | H               | L               | L               | L               | H               | DOUT      | High-Z     | $I_{CC}$              |
|                 | H               | L               | L               | H               | L               | High-Z    | DOUT       |                       |
|                 | H               | L               | L               | L               | L               | DOUT      | DOUT       |                       |
| Write           | L               | L               | X               | L               | H               | DIN       | High-Z     | $I_{CC}$              |
|                 | L               | L               | X               | H               | L               | High-Z    | DIN        |                       |
|                 | L               | L               | X               | L               | L               | DIN       | DIN        |                       |

## PIN CONFIGURATIONS

## 44-Pin TSOP (Type II) and SOJ

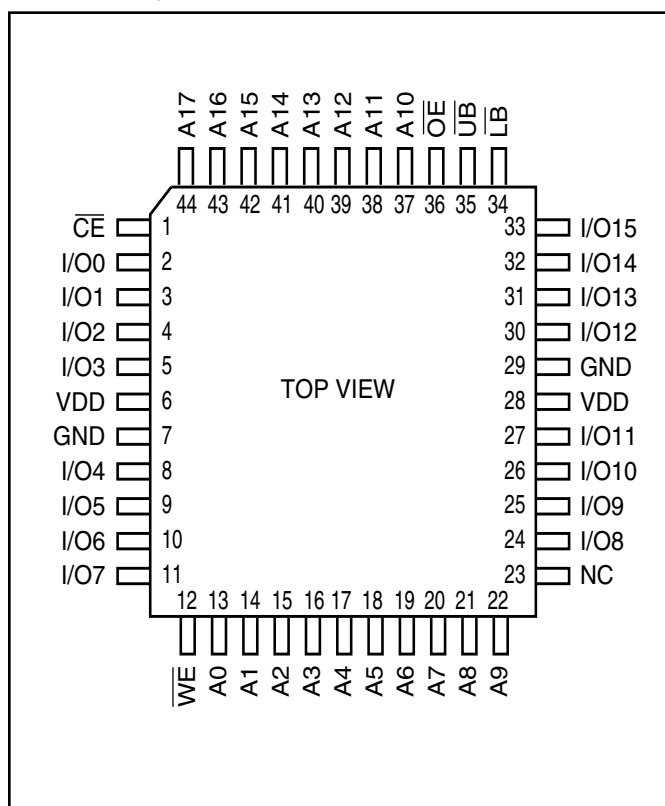


## PIN DESCRIPTIONS

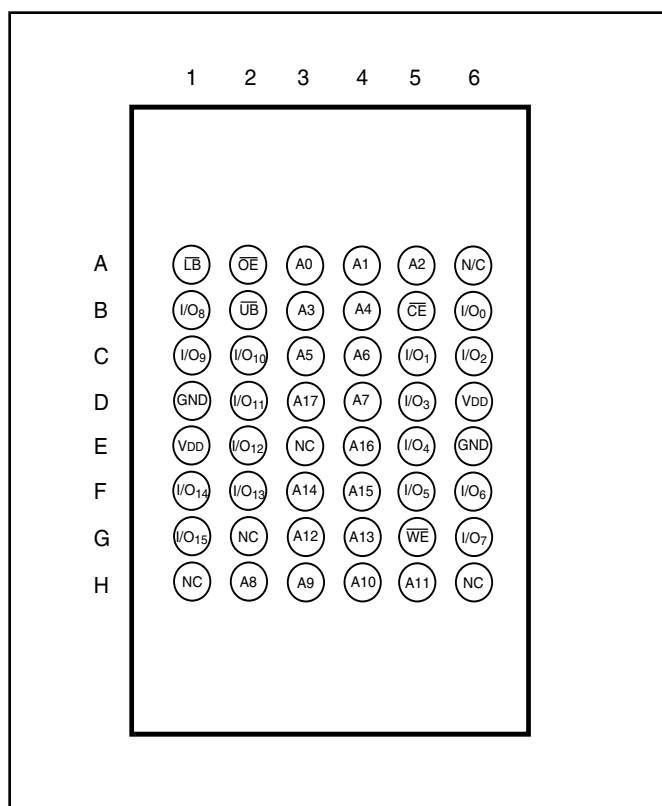
|                 |                                 |
|-----------------|---------------------------------|
| A0-A17          | Address Inputs                  |
| I/O0-I/O15      | Data Inputs/Outputs             |
| $\overline{CE}$ | Chip Enable Input               |
| $\overline{OE}$ | Output Enable Input             |
| $\overline{WE}$ | Write Enable Input              |
| $\overline{LB}$ | Lower-byte Control (I/O0-I/O7)  |
| $\overline{UB}$ | Upper-byte Control (I/O8-I/O15) |
| NC              | No Connection                   |
| $V_{DD}$        | Power                           |
| GND             | Ground                          |

## PIN CONFIGURATIONS

## 44-Pin LQFP



## 48-Pin mini BGA



## PIN DESCRIPTIONS

|                 |                                 |
|-----------------|---------------------------------|
| A0-A17          | Address Inputs                  |
| I/O0-I/O15      | Data Inputs/Outputs             |
| $\overline{CE}$ | Chip Enable Input               |
| $\overline{OE}$ | Output Enable Input             |
| $\overline{WE}$ | Write Enable Input              |
| $\overline{LB}$ | Lower-byte Control (I/O0-I/O7)  |
| $\overline{UB}$ | Upper-byte Control (I/O8-I/O15) |
| NC              | No Connection                   |
| V <sub>DD</sub> | Power                           |
| GND             | Ground                          |

**ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>**

| Symbol            | Parameter                            | Value                        | Unit |
|-------------------|--------------------------------------|------------------------------|------|
| V <sub>TERM</sub> | Terminal Voltage with Respect to GND | −0.5 to V <sub>DD</sub> +0.5 | V    |
| T <sub>STG</sub>  | Storage Temperature                  | −65 to +150                  | °C   |
| P <sub>T</sub>    | Power Dissipation                    | 1.0                          | W    |

**Note:**

1. Stress greater than those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect reliability.

**OPERATING RANGE**

| Range      | Ambient Temperature | V <sub>DD</sub> |            |
|------------|---------------------|-----------------|------------|
|            |                     | 10ns            | 12ns       |
| Commercial | 0°C to +70°C        | 3.3V +10%, -5%  | 3.3V ± 10% |
| Industrial | −40°C to +85°C      | 3.3V +10%, -5%  | 3.3V ± 10% |

**DC ELECTRICAL CHARACTERISTICS** (Over Operating Range)

| Symbol          | Parameter                        | Test Conditions                                              | Min.         | Max.                  | Unit |
|-----------------|----------------------------------|--------------------------------------------------------------|--------------|-----------------------|------|
| V <sub>OH</sub> | Output HIGH Voltage              | V <sub>DD</sub> = Min., I <sub>OH</sub> = −4.0 mA            | 2.4          | —                     | V    |
| V <sub>OL</sub> | Output LOW Voltage               | V <sub>DD</sub> = Min., I <sub>OL</sub> = 8.0 mA             | —            | 0.4                   | V    |
| V <sub>IH</sub> | Input HIGH Voltage               |                                                              | 2.0          | V <sub>DD</sub> + 0.3 | V    |
| V <sub>IL</sub> | Input LOW Voltage <sup>(1)</sup> |                                                              | −0.3         | 0.8                   | V    |
| I <sub>LI</sub> | Input Leakage                    | GND ≤ V <sub>IN</sub> ≤ V <sub>DD</sub>                      | Com.<br>Ind. | −2<br>5               | μA   |
| I <sub>LO</sub> | Output Leakage                   | GND ≤ V <sub>OUT</sub> ≤ V <sub>DD</sub><br>Outputs Disabled | Com.<br>Ind. | −2<br>5               | μA   |

**Notes:**

1. V<sub>IL</sub> (min.) = −2.0V for pulse width less than 10 ns.

**POWER SUPPLY CHARACTERISTICS<sup>(1)</sup>** (Over Operating Range)

| Symbol           | Parameter                                        | Test Conditions                                                                                                    | -10  |      | -12  |      | Unit |
|------------------|--------------------------------------------------|--------------------------------------------------------------------------------------------------------------------|------|------|------|------|------|
|                  |                                                  |                                                                                                                    | Min. | Max. | Min. | Max. |      |
| I <sub>CC</sub>  | V <sub>DD</sub> Dynamic Operating Supply Current | V <sub>DD</sub> = Max., Com.                                                                                       | —    | 100  | —    | 90   | mA   |
|                  |                                                  | I <sub>OUT</sub> = 0 mA, f = f <sub>MAX</sub> Ind.                                                                 | —    | 110  | —    | 100  |      |
| I <sub>SB</sub>  | TTL Standby Current (TTL Inputs)                 | V <sub>DD</sub> = Max., Com.                                                                                       | —    | 50   | —    | 45   | mA   |
|                  |                                                  | V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> Ind.<br>CE ≥ V <sub>IH</sub> , f = f <sub>MAX</sub> .         | —    | 55   | —    | 50   |      |
| I <sub>SB1</sub> | TTL Standby Current (TTL Inputs)                 | V <sub>DD</sub> = Max., Com.                                                                                       | —    | 20   | —    | 20   | mA   |
|                  |                                                  | V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> Ind.<br>CE ≥ V <sub>IH</sub> , f = 0                          | —    | 25   | —    | 25   |      |
| I <sub>SB2</sub> | CMOS Standby Current (CMOS Inputs)               | V <sub>DD</sub> = Max., Com.                                                                                       | —    | 15   | —    | 15   | mA   |
|                  |                                                  | CE ≥ V <sub>DD</sub> - 0.2V, Ind.<br>V <sub>IN</sub> ≥ V <sub>DD</sub> - 0.2V, or<br>V <sub>IN</sub> ≤ 0.2V, f = 0 | —    | 20   | —    | 20   |      |

**Note:**

1. At f = f<sub>MAX</sub>, address and data inputs are cycling at the maximum frequency, f = 0 means no input lines change.  
Shaded area product in development

**CAPACITANCE<sup>(1)</sup>**

| Symbol           | Parameter                | Conditions            | Max. | Unit |
|------------------|--------------------------|-----------------------|------|------|
| C <sub>IN</sub>  | Input Capacitance        | V <sub>IN</sub> = 0V  | 6    | pF   |
| C <sub>OUT</sub> | Input/Output Capacitance | V <sub>OUT</sub> = 0V | 8    | pF   |

**Note:**

1. Tested initially and after any design or process changes that may affect these parameters.

**READ CYCLE SWITCHING CHARACTERISTICS<sup>(1)</sup>** (Over Operating Range)

| Symbol                           | Parameter                                                     | -10  |      | -12  |      | Unit |
|----------------------------------|---------------------------------------------------------------|------|------|------|------|------|
|                                  |                                                               | Min. | Max. | Min. | Max. |      |
| t <sub>RC</sub>                  | Read Cycle Time                                               | 10   | —    | 12   | —    | ns   |
| t <sub>AA</sub>                  | Address Access Time                                           | —    | 10   | —    | 12   | ns   |
| t <sub>OH</sub>                  | Output Hold Time                                              | 2    | —    | 2    | —    | ns   |
| t <sub>ACE</sub>                 | $\overline{\text{CE}}$ Access Time                            | —    | 10   | —    | 12   | ns   |
| t <sub>DOE</sub>                 | $\overline{\text{OE}}$ Access Time                            | —    | 4    | —    | 5    | ns   |
| t <sub>HZOE</sub> <sup>(2)</sup> | $\overline{\text{OE}}$ to High-Z Output                       | —    | 4    | —    | 5    | ns   |
| t <sub>LZOE</sub> <sup>(2)</sup> | $\overline{\text{OE}}$ to Low-Z Output                        | 0    | —    | 0    | —    | ns   |
| t <sub>HZCE</sub> <sup>(2)</sup> | $\overline{\text{CE}}$ to High-Z Output                       | 0    | 4    | 0    | 6    | ns   |
| t <sub>LZCE</sub> <sup>(2)</sup> | $\overline{\text{CE}}$ to Low-Z Output                        | 3    | —    | 3    | —    | ns   |
| t <sub>BA</sub>                  | $\overline{\text{LB}}, \overline{\text{UB}}$ Access Time      | —    | 4    | —    | 5    | ns   |
| t <sub>HZB</sub> <sup>(2)</sup>  | $\overline{\text{LB}}, \overline{\text{UB}}$ to High-Z Output | 0    | 3    | 0    | 4    | ns   |
| t <sub>LZB</sub> <sup>(2)</sup>  | $\overline{\text{LB}}, \overline{\text{UB}}$ to Low-Z Output  | 0    | —    | 0    | —    | ns   |
| t <sub>PU</sub>                  | Power Up Time                                                 | 0    | —    | 0    | —    | ns   |
| t <sub>PD</sub>                  | Power Down Time                                               | —    | 10   | —    | 12   | ns   |

**Notes:**

1. Test conditions assume signal transition times of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0V to 3.0V and output loading specified in Figure 1.
2. Tested with the load in Figure 2. Transition is measured  $\pm 500$  mV from steady-state voltage.

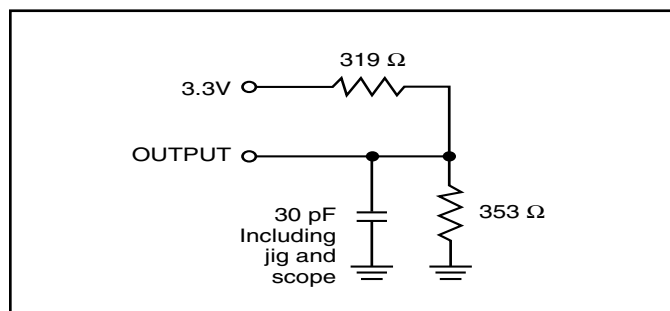
**AC TEST LOADS**

Figure 1

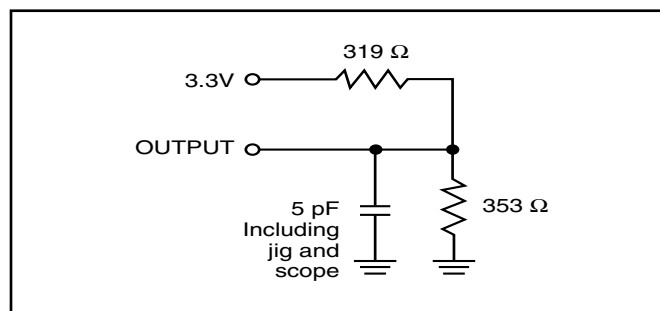


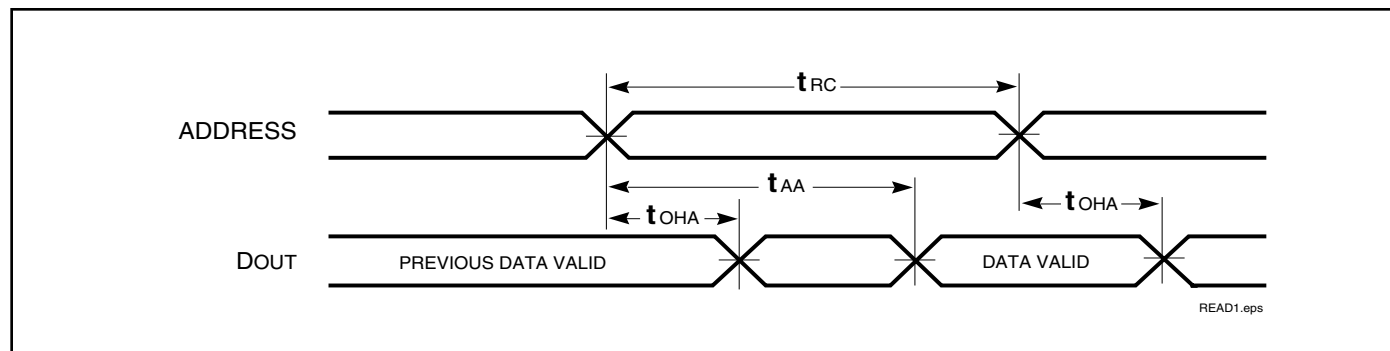
Figure 2

**AC TEST CONDITIONS**

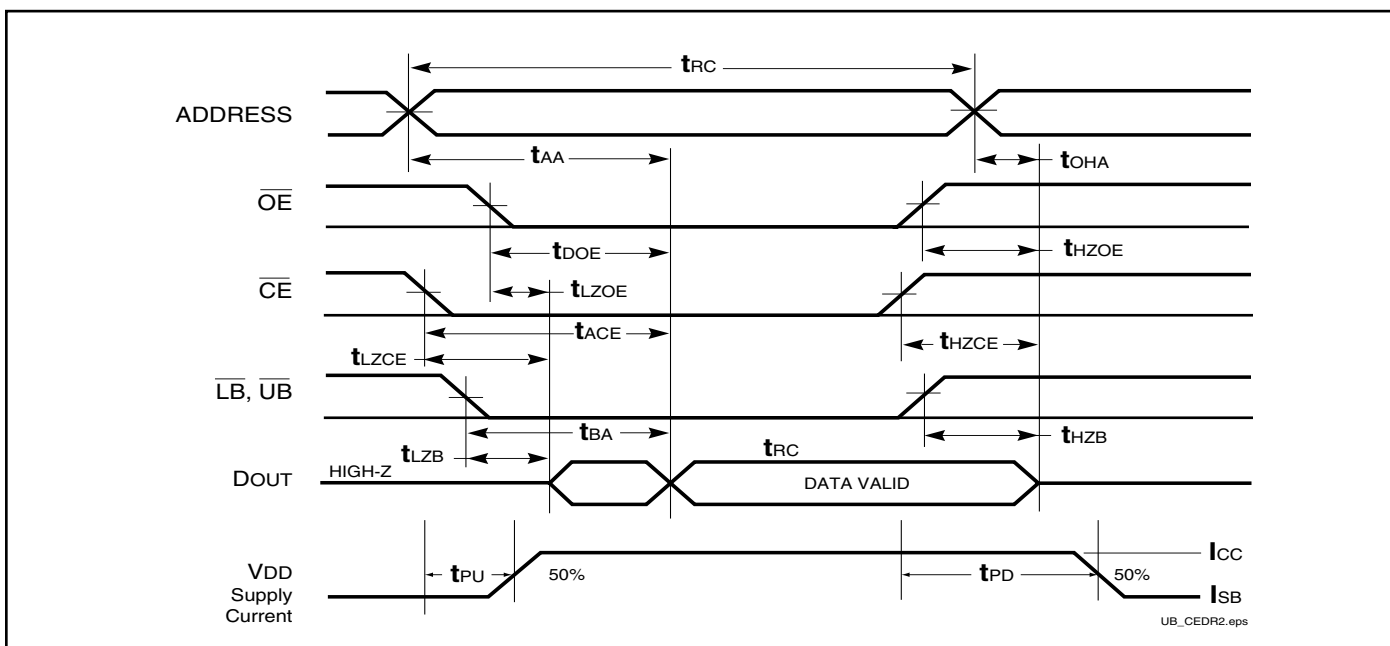
| Parameter                                   | Unit                |
|---------------------------------------------|---------------------|
| Input Pulse Level                           | 0V to 3.0V          |
| Input Rise and Fall Times                   | 3 ns                |
| Input and Output Timing and Reference Level | 1.5V                |
| Output Load                                 | See Figures 1 and 2 |

## AC WAVEFORMS

**READ CYCLE NO. 1<sup>(1,2)</sup>** (Address Controlled) ( $\overline{CE} = \overline{OE} = V_{IL}$ ,  $\overline{UB}$  or  $\overline{LB} = V_{IL}$ )

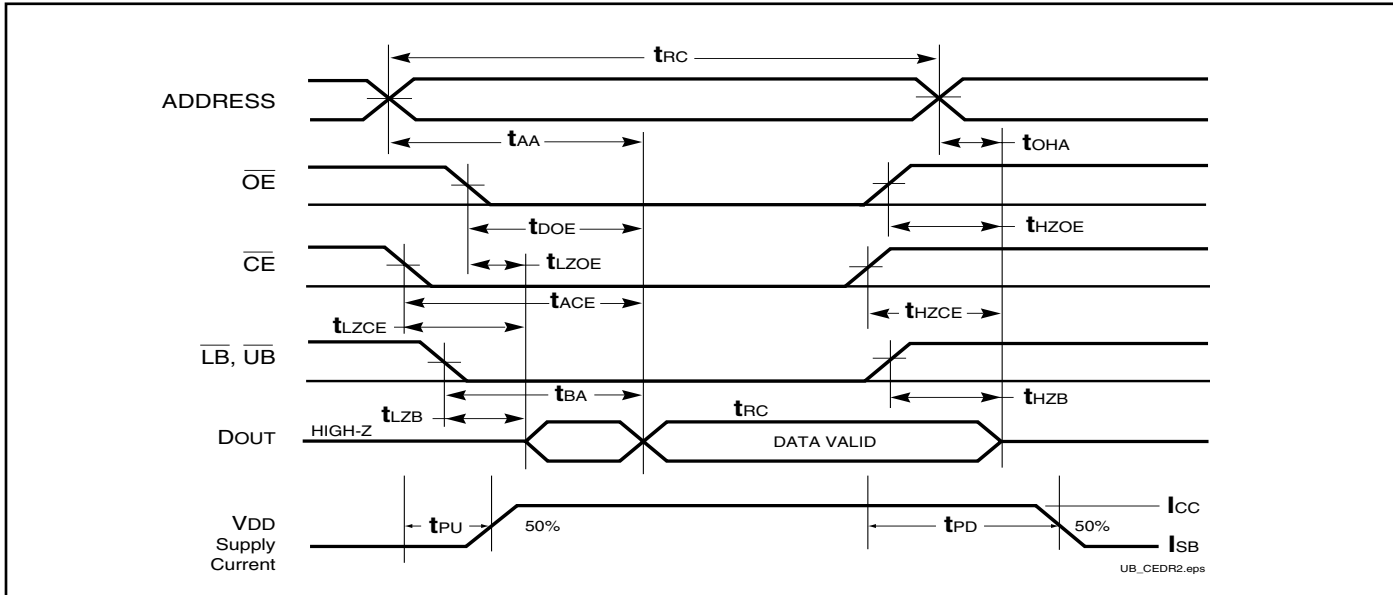


**READ CYCLE NO. 2<sup>(1,3)</sup>**



**Notes:**

1.  $\overline{WE}$  is HIGH for a Read Cycle.
2. The device is continuously selected.  $\overline{OE}$ ,  $\overline{CE}$ ,  $\overline{UB}$ , or  $\overline{LB} = V_{IL}$ .
3. Address is valid prior to or coincident with  $\overline{CE}$  LOW transition.

READ CYCLE NO. 2<sup>(1,3)</sup>**Notes:**

1.  $\overline{WE}$  is HIGH for a Read Cycle.
2. The device is continuously selected.  $\overline{OE}$ ,  $\overline{CE}$ ,  $\overline{UB}$ , or  $\overline{LB}$  =  $V_{IL}$ .
3. Address is valid prior to or coincident with  $\overline{CE}$  LOW transition.

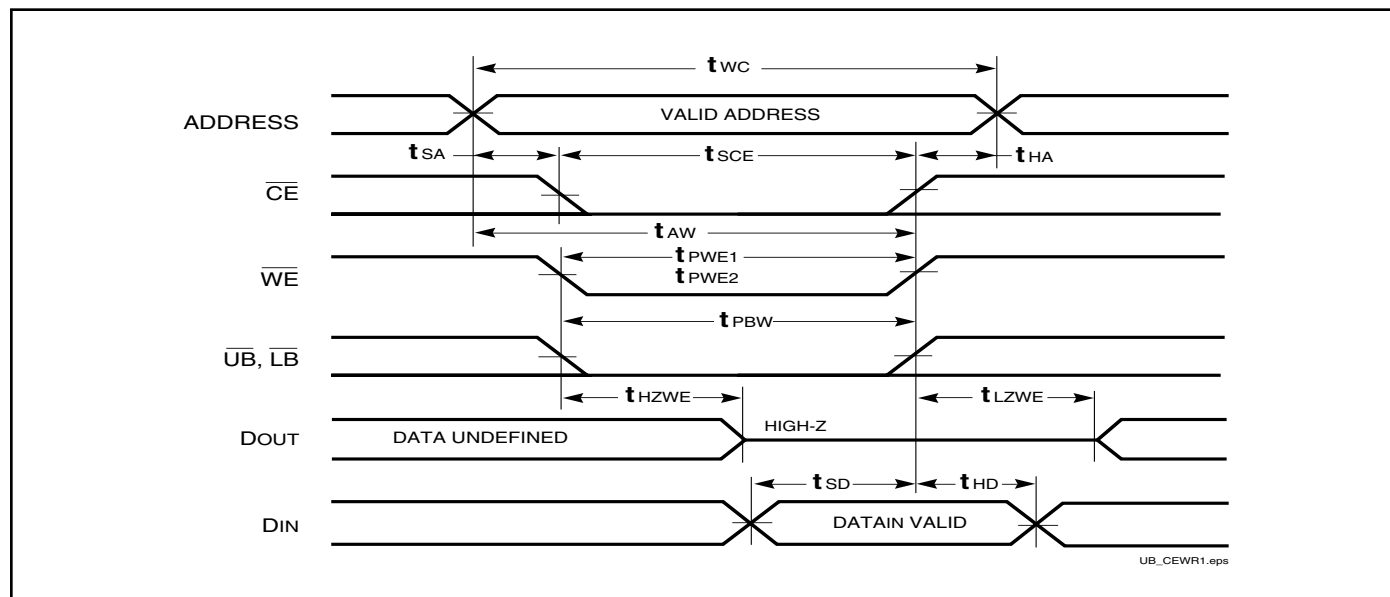
**WRITE CYCLE SWITCHING CHARACTERISTICS<sup>(1,3)</sup> (Over Operating Range)**

| Symbol                           | Parameter                                               | -10  |      | -12  |      | Unit |
|----------------------------------|---------------------------------------------------------|------|------|------|------|------|
|                                  |                                                         | Min. | Max. | Min. | Max. |      |
| t <sub>WC</sub>                  | Write Cycle Time                                        | 10   | —    | 12   | —    | ns   |
| t <sub>SCE</sub>                 | $\overline{CE}$ to Write End                            | 8    | —    | 8    | —    | ns   |
| t <sub>AW</sub>                  | Address Setup Time to Write End                         | 8    | —    | 8    | —    | ns   |
| t <sub>HA</sub>                  | Address Hold from Write End                             | 0    | —    | 0    | —    | ns   |
| t <sub>SA</sub>                  | Address Setup Time                                      | 0    | —    | 0    | —    | ns   |
| t <sub>PWB</sub>                 | $\overline{LB}$ , $\overline{UB}$ Valid to End of Write | 8    | —    | 8    | —    | ns   |
| t <sub>PWE1</sub>                | $\overline{WE}$ Pulse Width                             | 8    | —    | 8    | —    | ns   |
| t <sub>PWE2</sub>                | $\overline{WE}$ Pulse Width ( $\overline{OE}$ = LOW)    | 10   | —    | 12   | —    | ns   |
| t <sub>SD</sub>                  | Data Setup to Write End                                 | 6    | —    | 6    | —    | ns   |
| t <sub>HD</sub>                  | Data Hold from Write End                                | 0    | —    | 0    | —    | ns   |
| t <sub>HZWE</sub> <sup>(2)</sup> | $\overline{WE}$ LOW to High-Z Output                    | —    | 5    | —    | 6    | ns   |
| t <sub>LZWE</sub> <sup>(2)</sup> | $\overline{WE}$ HIGH to Low-Z Output                    | 2    | —    | 2    | —    | ns   |

**Notes:**

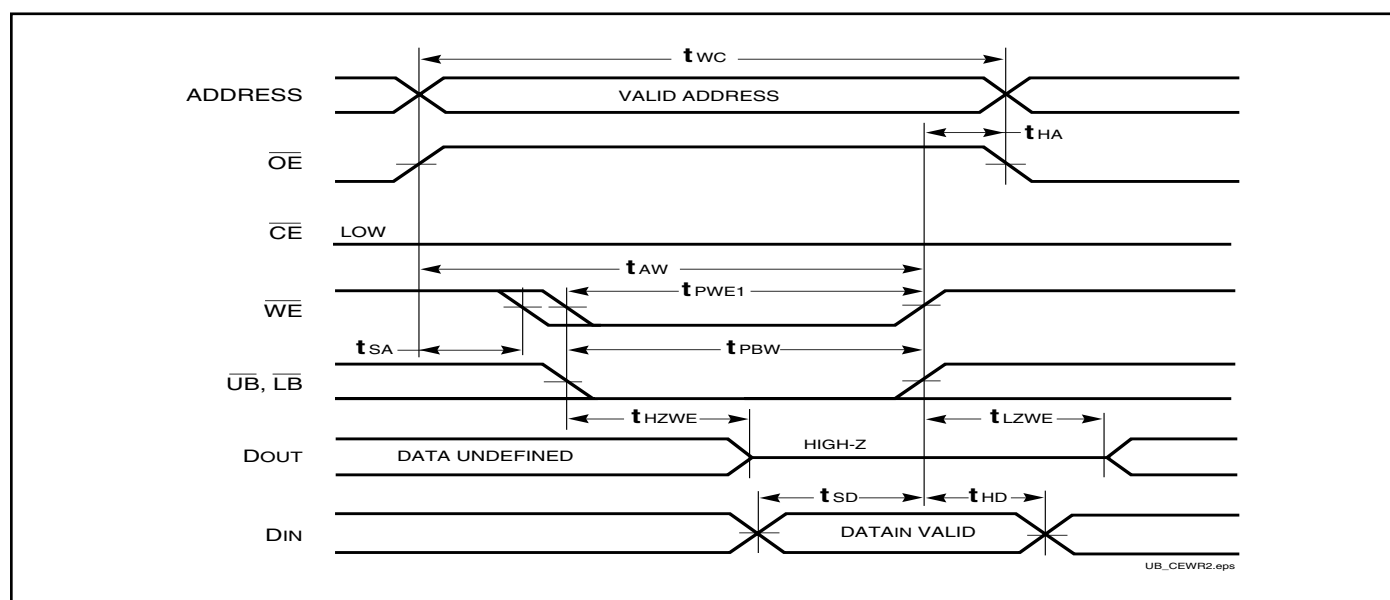
1. Test conditions assume signal transition times of 3 ns or less, timing reference levels of 1.5V, input pulse levels of 0V to 3.0V and output loading specified in Figure 1.
2. Tested with the load in Figure 2. Transition is measured  $\pm 500$  mV from steady-state voltage. Not 100% tested.
3. The internal write time is defined by the overlap of  $\overline{CE}$  LOW and  $\overline{UB}$  or  $\overline{LB}$  and  $\overline{WE}$  LOW. All signals must be in valid states to initiate a Write, but any one can go inactive to terminate the Write. The Data Input Setup and Hold timing are referenced to the rising or falling edge of the signal that terminates the write.

## AC WAVEFORMS

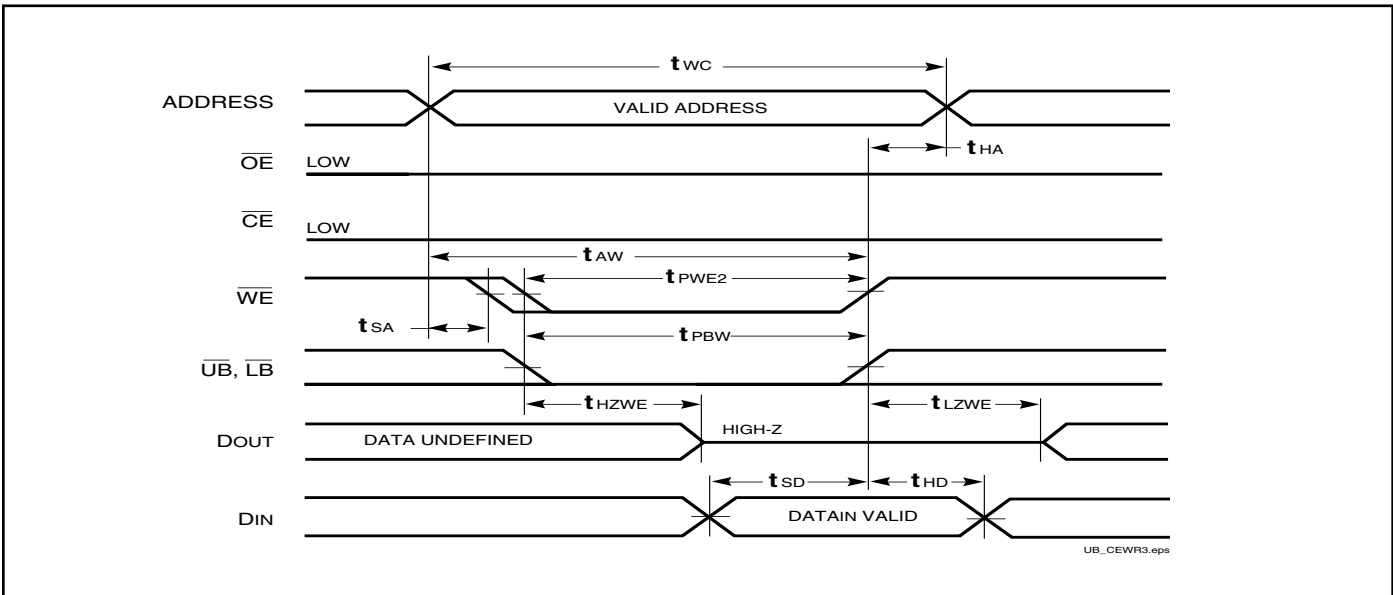
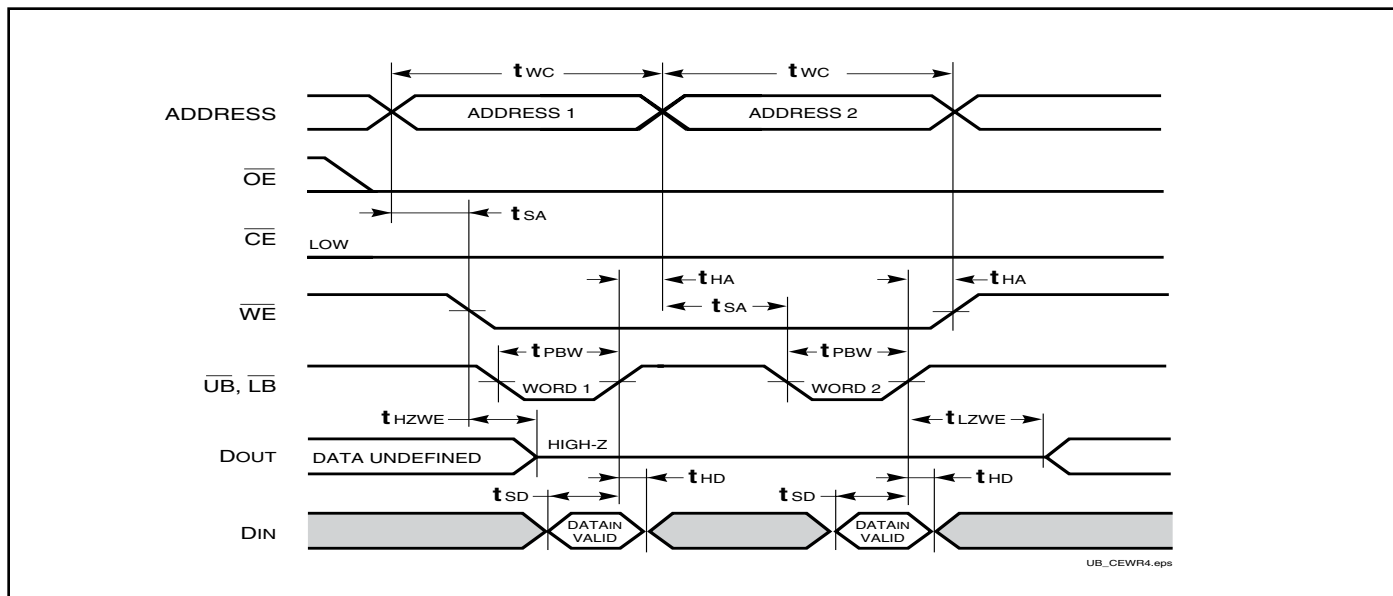
WRITE CYCLE NO. 1 ( $\overline{CE}$  Controlled,  $\overline{OE}$  is HIGH or LOW) <sup>(1)</sup>

## Notes:

1. WRITE is an internally generated signal asserted during an overlap of the LOW states on the  $\overline{CE}$  and  $\overline{WE}$  inputs and at least one of the  $\overline{LB}$  and  $\overline{UB}$  inputs being in the LOW state.
2. WRITE = ( $\overline{CE}$ ) [ ( $\overline{LB}$ ) = ( $\overline{UB}$ ) ] ( $\overline{WE}$ ).

WRITE CYCLE NO. 2 ( $\overline{WE}$  Controlled.  $\overline{OE}$  is HIGH During Write Cycle) <sup>(1,2)</sup>

## AC WAVEFORMS

WRITE CYCLE NO. 3 ( $\overline{WE}$  Controlled,  $\overline{OE}$  is LOW During Write Cycle) <sup>(1)</sup>WRITE CYCLE NO. 4 ( $\overline{LB}$ ,  $\overline{UB}$  Controlled, Back-to-Back Write) <sup>(1,3)</sup>

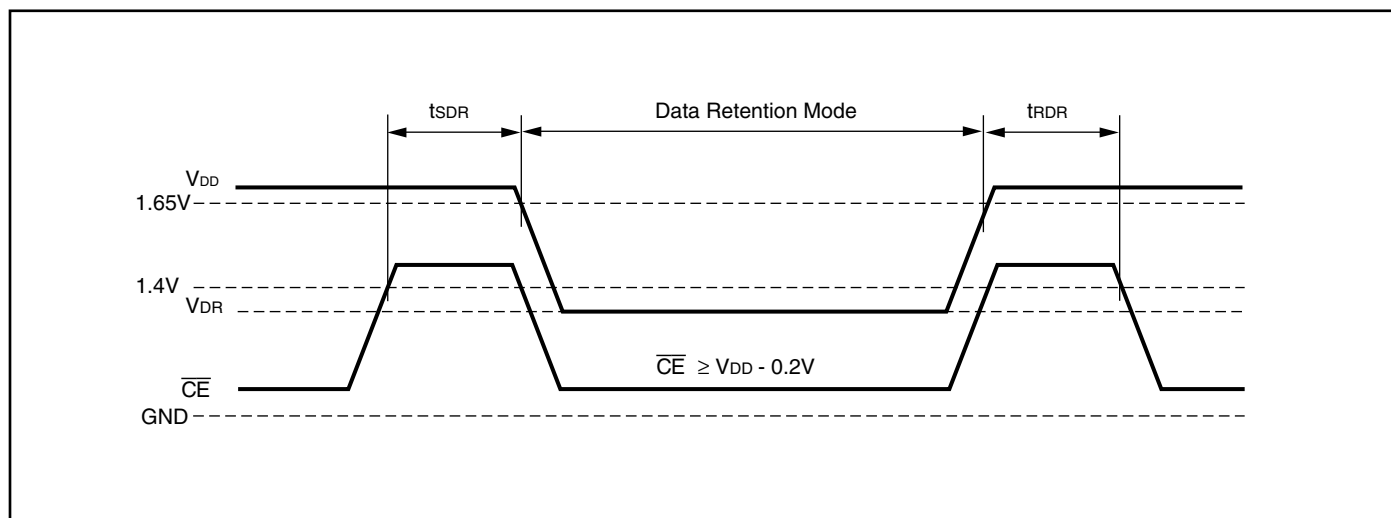
## Notes:

1. The internal Write time is defined by the overlap of  $\overline{CE} = \text{LOW}$ ,  $\overline{UB}$  and/or  $\overline{LB} = \text{LOW}$ , and  $\overline{WE} = \text{LOW}$ . All signals must be in valid states to initiate a Write, but any can be deasserted to terminate the Write. The  $t_{SA}$ ,  $t_{HA}$ ,  $t_{SD}$ , and  $t_{HD}$  timing is referenced to the rising or falling edge of the signal that terminates the Write.
2. Tested with  $\overline{OE}$  HIGH for a minimum of 4 ns before  $\overline{WE} = \text{LOW}$  to place the I/O in a HIGH-Z state.
3.  $\overline{WE}$  may be held LOW across many address cycles and the  $\overline{LB}$ ,  $\overline{UB}$  pins can be used to control the Write function.

**DATA RETENTION SWITCHING CHARACTERISTICS (LL)**

| Symbol    | Parameter                   | Test Condition                                       | Options      | Min.     | Typ. <sup>(1)</sup> | Max.     | Unit |
|-----------|-----------------------------|------------------------------------------------------|--------------|----------|---------------------|----------|------|
| $V_{DR}$  | $V_{DD}$ for Data Retention | See Data Retention Waveform                          |              | 2.0      | —                   | 3.6      | V    |
| $I_{DR}$  | Data Retention Current      | $V_{DD} = 2.0V$ , $\overline{CE} \geq V_{DD} - 0.2V$ | Com.<br>Ind. | —<br>—   | 5<br>—              | 10<br>15 | mA   |
| $t_{SDR}$ | Data Retention Setup Time   | See Data Retention Waveform                          |              | 0        | —                   | —        | ns   |
| $t_{RDR}$ | Recovery Time               | See Data Retention Waveform                          |              | $t_{RC}$ | —                   | —        | ns   |

**Note 1:** Typical values are measured at  $V_{DD} = 3.0V$ ,  $T_A = 25^\circ C$  and not 100% tested.

**DATA RETENTION WAVEFORM ( $\overline{CE}$  Controlled)**

## ORDERING INFORMATION

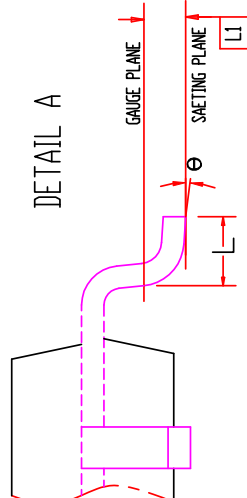
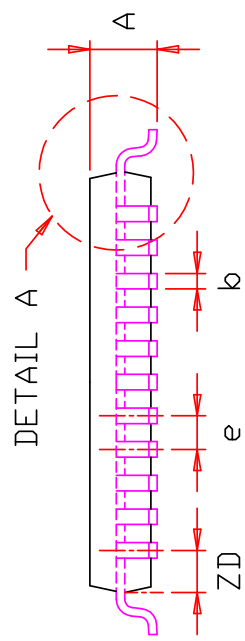
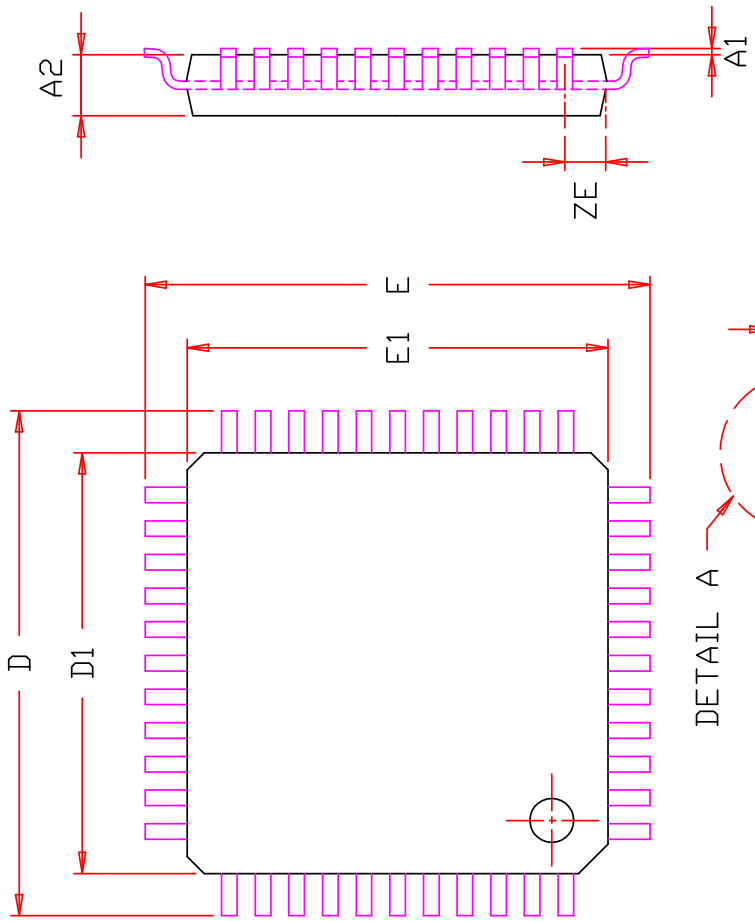
### Commercial Range: 0°C to +70°C

| Speed (ns) | Order Part No.     | Package                   |
|------------|--------------------|---------------------------|
| 10         | IS61LV25616AL-10T  | TSOP (Type II)            |
|            | IS61LV25616AL-10TL | TSOP (Type II), Lead-free |
|            | IS61LV25616AL-10K  | 400-mil SOJ               |
| 12         | IS61LV25616AL-12T  | TSOP (Type II)            |

### Industrial Range: -40°C to +85°C

| Speed (ns) | Order Part No.       | Package                          |
|------------|----------------------|----------------------------------|
| 10         | IS61LV25616AL-10TI   | TSOP (Type II)                   |
|            | IS61LV25616AL-10TLI  | TSOP (Type II), Lead-free        |
|            | IS61LV25616AL-10KI   | 400-mil SOJ                      |
|            | IS61LV25616AL-10KLI  | 400-mil SOJ, Lead-free           |
|            | IS61LV25616AL-10LQI  | LQFP                             |
|            | IS61LV25616AL-10LQLI | LQFP, Lead-free                  |
|            | IS61LV25616AL-10BI   | Mini BGA (8mm x 10mm)            |
|            | IS61LV25616AL-10BLI  | Mini BGA (8mm x 10mm), Lead-free |
| 12         | IS61LV25616AL-12TI   | TSOP (Type II)                   |

| SYMBOL | DIMENSION IN MM |       | DIMENSION IN INCH |       |
|--------|-----------------|-------|-------------------|-------|
|        | MIN.            | MAX.  | MIN.              | MAX.  |
| A      | 1.40            | 1.60  | 0.055             | 0.063 |
| A1     | 0.05            | 0.15  | 0.002             | 0.006 |
| A2     | 1.35            | 1.45  | 0.053             | 0.057 |
| b      | 0.30            | 0.45  | 0.012             | 0.018 |
| D      | 11.70           | 12.30 | 0.460             | 0.484 |
| D1     | 9.87            | 10.00 | 0.389             | 0.399 |
| E      | 11.70           | 12.30 | 0.460             | 0.484 |
| E1     | 9.87            | 10.00 | 0.389             | 0.399 |
| e      | 0.80            | BSC.  | 0.031             | BSC.  |
| L      | 0.45            | 0.60  | 0.018             | 0.024 |
| L1     | 0.25            | BSC.  | 0.010             | BSC.  |
| ZD     | 1.00            | REF.  | 0.039             | REF.  |
| ZE     | 1.00            | REF.  | 0.039             | REF.  |
| θ      | 0               | 3.5°  | 0                 | 3.5°  |

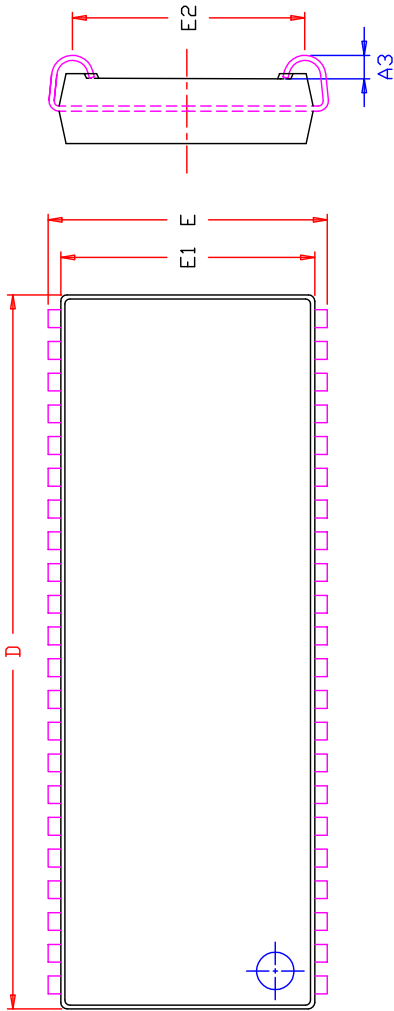


**NOTE :**

- 1. CONTROLLING DIMENSION : MM
- 2. DIMENSION D1 AND E1 DO NOT INCLUDE MOLD PROTRUSION.
- 3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION/INTRUSION.

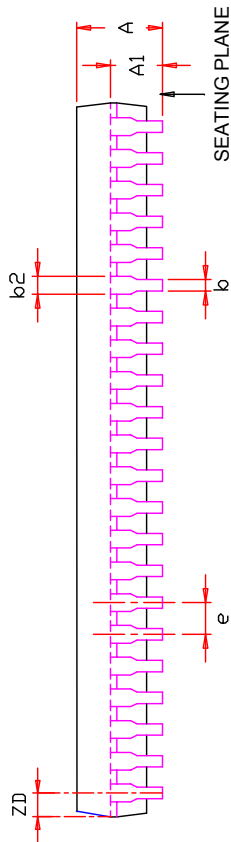
|             |       |                                              |  |  |      |   |      |            |
|-------------|-------|----------------------------------------------|--|--|------|---|------|------------|
| <i>ICSI</i> | TITLE | 44L 10x10x1.4mm LQFP<br>(Footprint : 2.0 mm) |  |  | REV. | C | DATE | 08/30/2001 |
|             |       | Package Outline                              |  |  |      |   |      |            |

| SYMBOL | DIMENSION IN MM |       |       | DIMENSION IN INCH |       |       |
|--------|-----------------|-------|-------|-------------------|-------|-------|
|        | MIN.            | NOM.  | MAX.  | MIN.              | NOM.  | MAX.  |
| A      | 3.25            | —     | 3.76  | 0.128             | —     | 0.148 |
| A1     | 2.08            | —     | —     | 0.082             | —     | —     |
| A3     | 0.635           | —     | —     | 0.025             | —     | —     |
| b      | 0.38            | —     | 0.51  | 0.015             | —     | 0.020 |
| b2     | 0.66            | 0.71  | 0.81  | 0.026             | 0.028 | 0.032 |
| D      | 28.45           | 28.58 | 28.70 | 1.120             | 1.125 | 1.130 |
| E      | 11.05           | 11.18 | 11.30 | 0.435             | 0.440 | 0.445 |
| E1     | 10.03           | 10.16 | 10.29 | 0.395             | 0.400 | 0.405 |
| E2     | 9.40            | BSC.  | —     | 0.370             | BSC.  | —     |
| e      | 1.27            | BSC.  | —     | 0.050             | BSC.  | —     |
| ZD     | 0.95            | REF.  | —     | 0.037             | REF.  | —     |



NOTE :

1. Controlling dimension : mm
2. Dimension D and E1 do not include mold protrusion .
3. Dimension b2 does not include dambar protrusion/intrusion.
4. Formed leads shall be planar with respect to one another within 0.1mm at the seating plane after final test.
5. Reference document : JEDEC SPEC MS-027.



TITLE

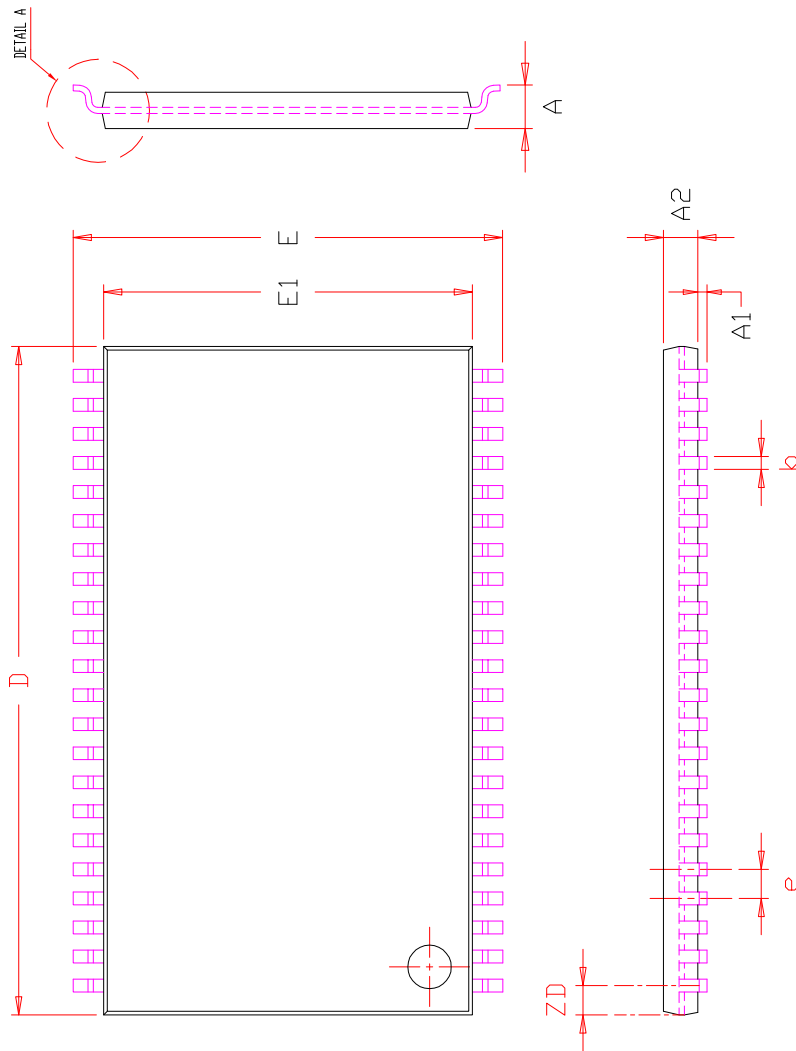
44L 400mil SOJ  
Package Outline

REV.

E

DATE

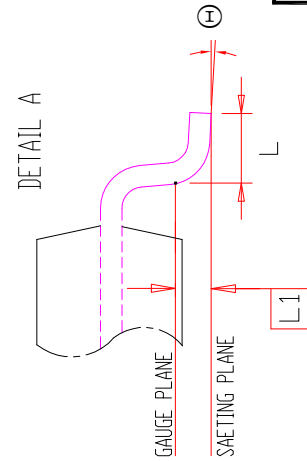
12/21/2007



| SYMBOL | DIMENSION IN MM |       |       | DIMENSION IN INCH |       |       |
|--------|-----------------|-------|-------|-------------------|-------|-------|
|        | MIN.            | NOM.  | MAX.  | MIN.              | NOM.  | MAX.  |
| A      | 1.00            |       | 1.20  | 0.039             |       | 0.047 |
| A1     | 0.05            |       | 0.15  | 0.002             |       | 0.006 |
| A2     | 0.95            | 1.00  | 1.05  | 0.037             | 0.039 | 0.041 |
| b      | 0.30            |       | 0.45  | 0.012             |       | 0.018 |
| D      | 18.28           | 18.41 | 18.54 | 0.720             | 0.725 | 0.730 |
| E      | 11.56           | 11.76 | 11.96 | 0.455             | 0.463 | 0.471 |
| E1     | 10.03           | 10.16 | 10.29 | 0.395             | 0.400 | 0.405 |
| e      |                 | 0.80  | BSC.  |                   | 0.031 | BSC.  |
| L      | 0.40            |       | 0.69  | 0.016             |       | 0.027 |
| L1     |                 | 0.25  | BSC.  |                   | 0.010 | BSC.  |
| ZD     |                 | 0.805 | REF.  |                   | 0.032 | REF.  |
| ⊖      | 0               |       | 8°    | 0                 |       | 8°    |

**NOTE :**

1. CONTROLLING DIMENSION : MM
2. DIMENSION D AND E1 DO NOT INCLUDE MOLD PROTRUSION.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION/INTRUSION.



|  |              |                                             |             |          |             |            |
|--|--------------|---------------------------------------------|-------------|----------|-------------|------------|
|  | <b>TITLE</b> | <b>44L 400mil TSOP-2</b><br>Package Outline | <b>REV.</b> | <b>F</b> | <b>DATE</b> | 06/04/2008 |
|--|--------------|---------------------------------------------|-------------|----------|-------------|------------|

